3D ICs Market - Global Industry Analysis, Size, Share, Growth, Trends, and Forecast, 2013 - 2019

Description: '3D ICs (MEMS and sensors, RF SiP, Optoelectronics and imaging, Memories, Logic, HB LED) Market - Global Industry Analysis, Size, Share, Growth, Trends, and Forecast, 2013 - 2019'

This report analyzes the 3D ICs market on a global basis, with further breakdown into various sub-segments. It provides cross-sectional analysis of the market based on parameters such as geography, system type, applications and networking technology. The analysis covers market estimates in terms of revenue and forecast for the period of 2013 to 2019.

The global 3D ICs market is going through a phase marked with complexity of technology and low awareness. Industries in this market need to effectively balance their expenditure between technology advancement and capacity expansion. The 3D ICs market is yet to achieve complete recognition. Its successful penetration into various end-user sectors is mainly administered by research and development initiatives. There are variations in growth pattern across different geographies. These variations exist in terms of technologies used and applications preferred.

This report is thereby produced to give a detailed overview of the ongoing trends in the market. It includes a review of market dynamics with focus on market drivers, growth challenges (restraints), and opportunities. The value chain analysis and Porter's five forces analysis included in the report further help in assessing the market situation and competitiveness. Market attractiveness analysis highlights key segments of the market and their comparative attractiveness against other segments.

Apart from the detailed sub-segment analysis as mentioned below, this report also provides company profiles of key market players. The competitive profiling of these players includes company and financial overview, business strategies adopted by them, and their recent developments which can help in assessing competition in the market. Major companies included in this report are Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), Xilinx Inc., 3M Company, Micron Technology Inc., (Elpida Memory Inc.), Ziptronix, Inc., Tezzaron Semiconductor Corporation, MonolithIC 3D Inc., STATS ChipPAC Ltd. and United Microelectronics Corporation (UMC).

This report analyzes the global 3D ICs market in terms of revenue (USD million). The market has been segmented as follows:

- **End-Use Sectors**
  - Consumer electronics
  - Information and communication technology
  - Transport (automotive and aerospace)
  - Military
  - Others (Biomedical applications and R&D)

- **Substrate Type:**
  - Silicon on insulator (SOI)
  - Bulk Silicon

- **Fabrication Process:**
  - Beam re-crystallization
  - Wafer bonding
  - Silicon epitaxial growth
  - Solid phase crystallization

Product
- MEMS and Sensor
- RF SIP
- Optoelectronics and imaging
- Memories (3D Stacks)
- Logic (3D Sip/Soc)
- HB LED

Geography

North America
Europe
Asia Pacific
Rest of World (RoW)

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